502545416 10/25/2013

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2590933

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ching-Ling Lin	09/10/2013
Chih-Sen Huang	10/18/2013
Po-Chao Tsao	10/18/2013
Ching-Wen Hung	10/18/2013
Jia-Rong Wu	09/10/2013
Chien-Ting Lin	10/18/2013

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14062909

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	NAUP1992USA
NAME OF SUBMITTER:	SHELLEY KUO

PATENT REEL: 031474 FRAME: 0789 CH \$40 00

502545416

Signature:	/SHELLEY KUO/		
Date: 10/25/2013			
Total Attachments: 12			
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PATENT REEL: 031474 FRAME: 0790

Title of Invention: METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	_filed on,	, or
□ PCT international application	number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTROICORP.	NICS having a postal add	ress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE" below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	00), the receipt of which is her	reby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-	rhich are disclosed in the ent to be obtained for said in-part, divisions, renewals,	EE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	ice has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven- known and accessible to I and will te related thereto and will promptly exe-	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have he	lication, said invention and said l cessary or desirable to carry out	Letters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this			

Page 1 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Ching-Ling Lin	Date:	2013.9.10.	
Signature:	Ching-Ling lin			

Page 2 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

Title of Invention:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or				
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□ PCT international application	n number	file	ed on	
The above-identified application was	s made or authorized to b	e made by me.		
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I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in isonment of not more tha	this declaration n five (5) years,	ı is punishab or both.	le
In consideration of the payment by	UNITED MICROELE CORP.	CTRONICS	having a po	ostal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Pa	ırk, Hsin-Chu	− ı City 300, ˈ	Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Doll nd valuable consideration	ar (\$ 1.00), the	receipt of wh	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improve ition and, in and to, all Lei r any continuations, contii	ments which are tters Patent to b nuation-in-part,	e disclosed ir e obtained fo divisions, ren	n the or said newals.
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or end n this assignment;	cumbrance has	been or will b	oe made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Pate estify as to the same in an	ent and legal eq v interference. I	uivalents as	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention ar ecessary or desirable to ca	nd said Letters F arry out the prop	Patent and sa	aid f. _(Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), in s form. Use this form for <u>e</u>	cluding naming	the entire	

Page 3 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

LEGAL NA	ME OF INVENTOR (ASSIGNOR)		
Inventor:	Chih-Sen Huang	Date:	OCT 18 2013
Signature:	Chih-Sen Huan	4	
	•	T .	

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276 Page 4 of 12

F#NPO-P0002E-US1201 DSC0-102U008977

PATENT REEL: 031474 FRAME: 0794

Title of Invention: METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this decisionment of not more than five (5)	laration is punishable) years, or both.	
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiwa	ın, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	0), the receipt of which is h	nereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals,	
I hereby covenant that no assignment entered into which would conflict with		ce has been or will be mad	le or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and i stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	e
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said Lacessary or desirable to carry out	etters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 5 of 12

LEGAL NAM	ME OF INVENTOR (ASSIGNO		•
Inventor:	Po-Chao Tsao	Date:	NCT 18 2013
Signature:	Ro- Chave . Jans		

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276 Page 6 of 12

Title of Invention: METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

As the helew named inventor I here	by do along that		
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☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
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I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	ice has been or will be made	or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	olication, said invention and said Lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for <u>each ad</u>	naming the entire ditional inventor.	

Page 7 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

LEGAL NA	ME OF INVENTOR (ASSIG	NOR)	1		
Inventor:	Ching-Wen Hung		Date:	OCT 18 2013	
Signature:	<u>Ching-Wen</u>	Hung	. i	:	

Page 8 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

Title of Invention:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

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I hereby sell, assign and transfer to the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, ar	nd to any and all improvemention and, in and to, all Letter any continuations, continu	ents which are ers Patent to b lation-in-part,	e disclosed in the e obtained for s divisions, renew	e aid ⁄als,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encu n this assignment;	mbrance has	been or will be r	made or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and ecessary or desirable to car	said Letters l ry out the pro	Patent and said poses thereof.	Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 9 of 12

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Jia-Rong Wu	•	Date:	2013.9.10		
Signature:	Jia-Rong	Wu				

Page 10 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

F#NPO-P0002E-US1201 DSC0-102U008977

PATENT REEL: 031474 FRAME: 0800

Title of Invention: METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

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representatives any and all papers, is maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said cessary or desirable to carry ou	Letters Patent and said it the proposes thereof.	e of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for <u>each a</u>	g naming the entire	

Page 11 of 12

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276

Inventor: Chien-Ting Lin

Signature: Chien Try Lin

Date: OCT 18 2013

NPO#NAU-P1992-USA:0 CUST#UMCD-2013-0276 Page 12 of 12

F#NPO-P0002E-US1201 DSC0-102U008977

PATENT REEL: 031474 FRAME: 0802

RECORDED: 10/25/2013